Part Number: APHK1608MGC MEGA GREEN

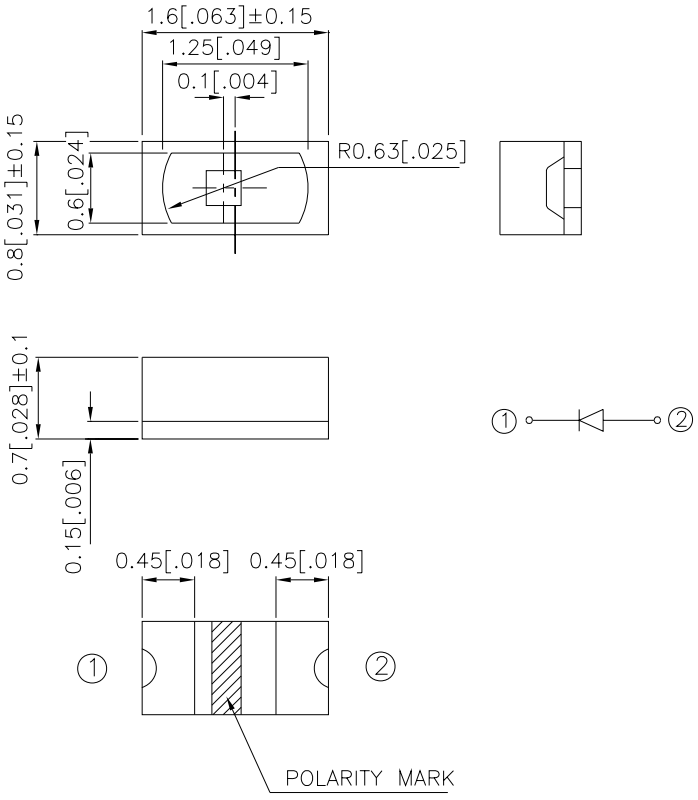
Features

- ●1.6mmx0.8mm SMT LED, 0.7mm THICKNESS.
- ●LOW POWER CONSUMPTION.
- ●WIDE VIEWING ANGLE.
- ●IDEAL FOR BACK LIGHT AND INDICATOR.
- ●VARIOUS COLORS AND LENS TYPES AVAILABLE.
- ●MOISTURE SENSITIVITY LEVEL : LEVEL 4.
- ●PACKAGE : 2000PCS / REEL.
- ●RoHS COMPLIANT.

Description

The Mega Green source color devices are made with DH InGaAlP on GaAs substrate Light Emitting Diode.

Package Dimensions



Notes:
1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.1(0.004") unless otherwise noted.
3.Specifications are subject to change without notice.

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2 θ 1/2
APHK1608MGC	MEGA GREEN (InGaAlP)	WATER CLEAR	36	90	90°

Notes:
1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.
2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at T_A=25°C

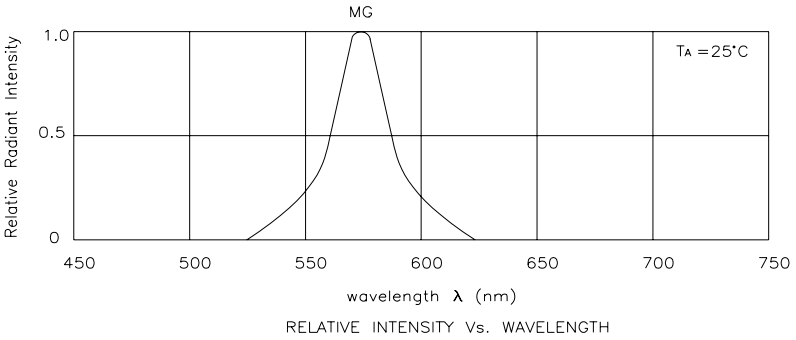
Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Mega Green	574		nm	I_F=20mA
λD [1]	Dominant Wavelength	Mega Green	568		nm	I_F=20mA
Δλ1/2	Spectral Line Half-width	Mega Green	26		nm	I_F=20mA
C	Capacitance	Mega Green	20		pF	V_F=0V;f=1MHz
V_F [2]	Forward Voltage	Mega Green	2.1	2.5	V	I_F=20mA
I_R	Reverse Current	Mega Green		10	uA	V_R = 5V

Notes:
1.Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at T_A=25°C

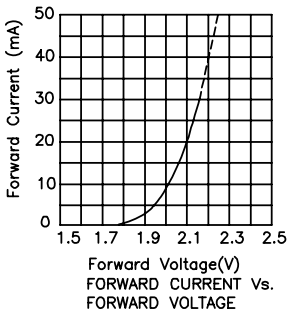
Parameter	Mega Green	Units
Power dissipation	105	mW
DC Forward Current	30	mA
Peak Forward Current [1]	150	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	

Note:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

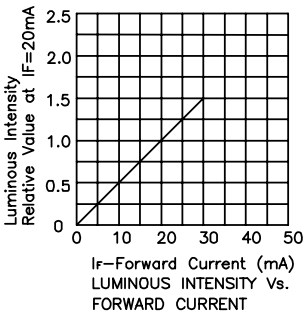


RELATIVE INTENSITY Vs. WAVELENGTH

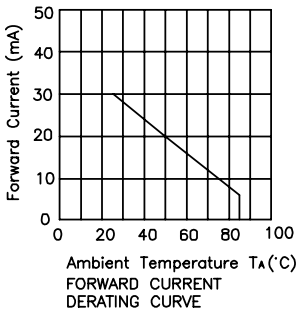
Mega Green **APHK1608MGC**



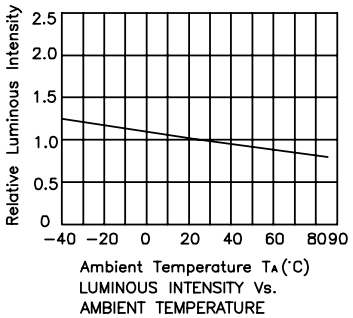
FORWARD CURRENT Vs.
FORWARD VOLTAGE



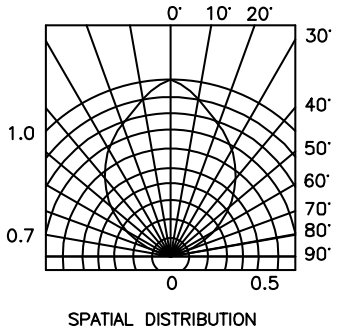
LUMINOUS INTENSITY Vs.
FORWARD CURRENT



FORWARD CURRENT
DERATING CURVE



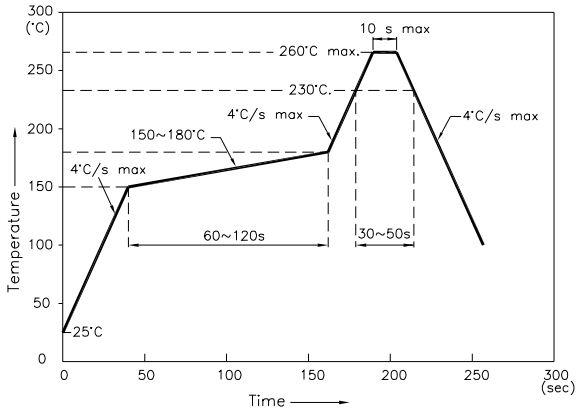
LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE



SPATIAL DISTRIBUTION

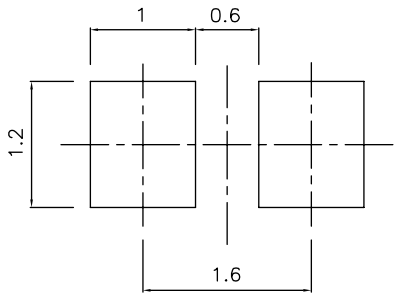
APHK1608MGC

Reflow Soldering Profile For Lead-free SMT Process.

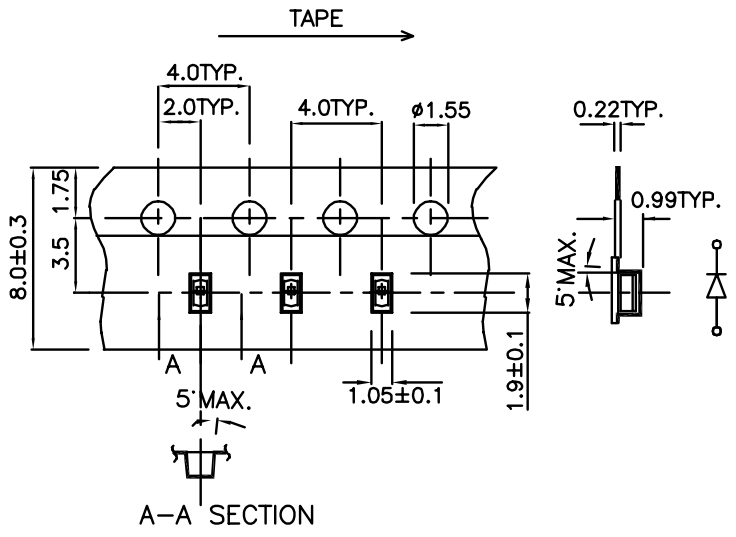
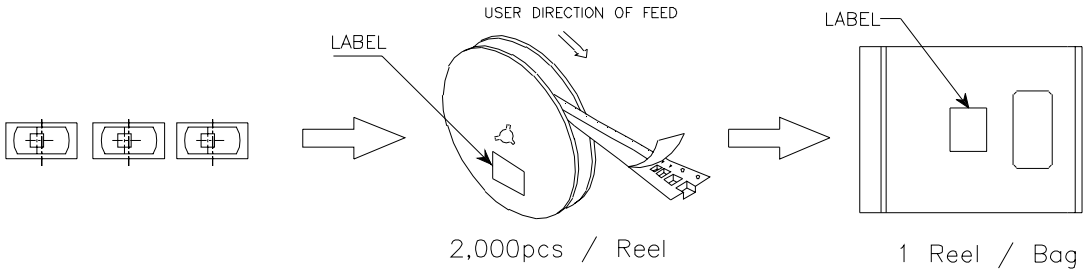
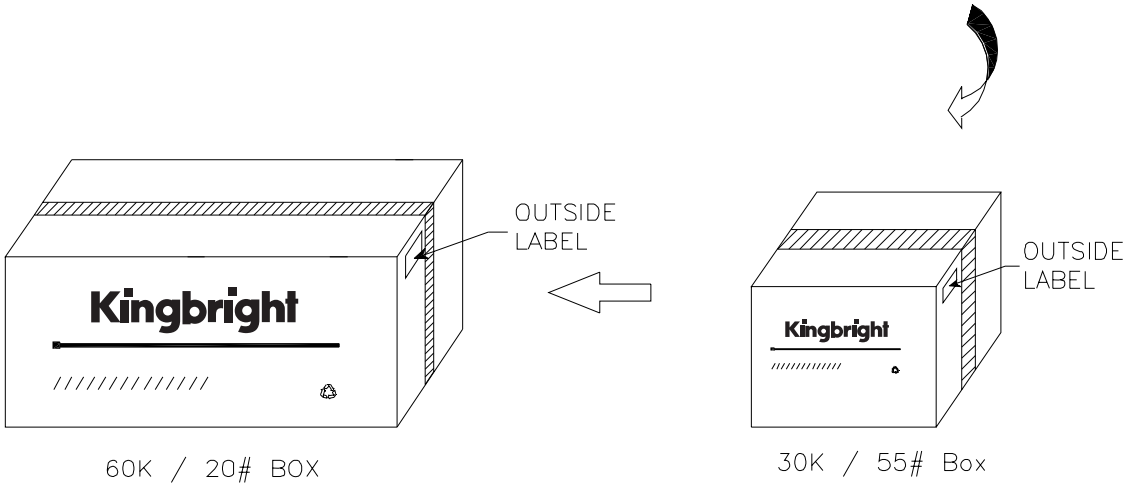
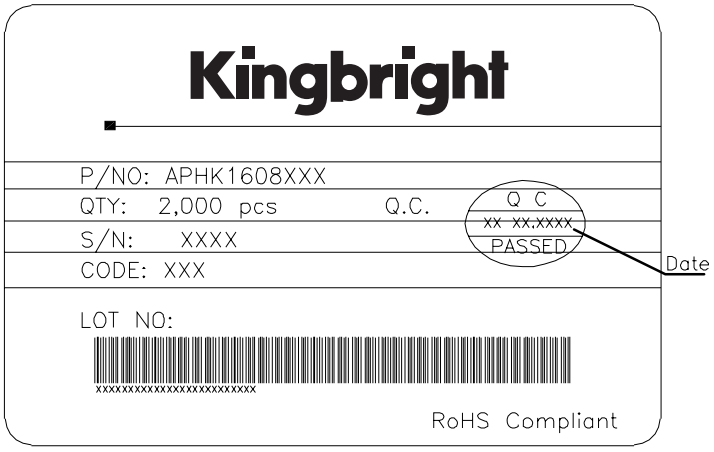


NOTES:
1. We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern
(Units: mm ; Tolerance: ± 0.1)



Tape Specifications
(Units : mm)



PACKING & LABEL SPECIFICATIONS **APHK1608MGC**